Attorney Docket No. 109263-132220 Intel No. P16322

REDISTRIBUTION OF SUBSTATE INTERCONNECTS

Abstract of the Disclosure

[0050] A first die/substrate is provided with a backside interconnect. A redistribution layer is provided between the first die/substrate and a second die/substrate that is stacked thereon, which includes a redistributed interconnect of the backside interconnect, coupled to and offset from the backside interconnect.